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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	11
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	16-VQFN Exposed Pad
Supplier Device Package	16-QFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f616-h-ml

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

MICROCHIP PIC16F610/616/16HV610/616

14-Pin Flash-Based, 8-Bit CMOS Microcontrollers

High-Performance RISC CPU:

- Only 35 Instructions to Learn:
 - All single-cycle instructions except branches
- Operating Speed:
 - DC 20 MHz oscillator/clock input
 - DC 200 ns instruction cycle
- Interrupt Capability
- 8-Level Deep Hardware Stack
- Direct, Indirect and Relative Addressing modes

Special Microcontroller Features:

- Precision Internal Oscillator:
- Factory calibrated to ±1%, typical
- User selectable frequency: 4 MHz or 8 MHz
- Power-Saving Sleep mode
- Voltage Range:
 - PIC16F610/616: 2.0V to 5.5V
 - PIC16HV610/616: 2.0V to user defined maximum (see note)
- Industrial and Extended Temperature Range
- Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Reset (BOR)
- Watchdog Timer (WDT) with Independent Oscillator for Reliable Operation
- Multiplexed Master Clear with Pull-up/Input Pin
- Programmable Code Protection
- High Endurance Flash:
 - 100,000 write Flash endurance
 - Flash retention: > 40 years

Low-Power Features:

Standby Current:

Note:

- 50 nA @ 2.0V, typical
- Operating Current:
 - 20 μA @ 32 kHz, 2.0V, typical

cannot exceed 5V.

Voltage across internal shunt regulator

- 220 μA @ 4 MHz, 2.0V, typical
- Watchdog Timer Current:
 - 1 μA @ 2.0V, typical

Peripheral Features:

- Shunt Voltage Regulator (PIC16HV610/616 only):
 - 5 volt regulation
 - 4 mA to 50 mA shunt range
- 11 I/O Pins and 1 Input Only
 - High current source/sink for direct LED drive
 - Interrupt-on-Change pins
 - Individually programmable weak pull-ups
- Analog Comparator module with:
 - Two analog comparators
 - Programmable on-chip voltage reference (CVREF) module (% of VDD)
 - Fixed Voltage Reference
 - Comparator inputs and outputs externally accessible
 - SR Latch
 - Built-In Hysteresis (user selectable)
- Timer0: 8-Bit Timer/Counter with 8-Bit Programmable Prescaler
- Enhanced Timer1:
 - 16-bit timer/counter with prescaler
 - External Timer1 Gate (count enable)
 - Option to use OSC1 and OSC2 in LP mode as Timer1 oscillator if INTOSC mode selected
 - Timer1 oscillator
- In-Circuit Serial Programming[™] (ICSP[™]) via Two Pins

PIC16F616/16HV616 only:

- A/D Converter:
 - 10-bit resolution
 - 8 external input channels
 - 2 internal reference channels
- Timer2: 8-Bit Timer/Counter with 8-Bit Period Register, Prescaler and Postscaler
- Enhanced Capture, Compare, PWM module:
 - 16-bit Capture, max. resolution 12.5 ns
 - 16-bit Compare, max. resolution 200 ns
 - 10-bit PWM with 1, 2 or 4 output channels, programmable "dead time", max. frequency 20 kHz





3.0 OSCILLATOR MODULE

3.1 Overview

The Oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 3-1 illustrates a block diagram of the Oscillator module.

Clock sources can be configured from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be configured with a choice of two selectable speeds: internal or external system clock source.

The Oscillator module can be configured in one of eight clock modes.

- 1. EC External clock with I/O on OSC2/CLKOUT.
- 2. LP 32 kHz Low-Power Crystal mode.
- 3. XT Medium Gain Crystal or Ceramic Resonator Oscillator mode.
- 4. HS High Gain Crystal or Ceramic Resonator mode.
- 5. RC External Resistor-Capacitor (RC) with Fosc/4 output on OSC2/CLKOUT.
- 6. RCIO External Resistor-Capacitor (RC) with I/O on OSC2/CLKOUT.
- 7. INTOSC Internal oscillator with Fosc/4 output on OSC2 and I/O on OSC1/CLKIN.
- 8. INTOSCIO Internal oscillator with I/O on OSC1/CLKIN and OSC2/CLKOUT.

Clock Source modes are configured by the FOSC<2:0> bits in the Configuration Word register (CONFIG). The Internal Oscillator module provides a selectable system clock mode of either 4 MHz (Postscaler) or 8 MHz (INTOSC).





3.4.1.1 OSCTUNE Register

The oscillator is factory calibrated but can be adjusted in software by writing to the OSCTUNE register (Register 3-1). The default value of the OSCTUNE register is '0'. The value is a 5-bit two's complement number.

When the OSCTUNE register is modified, the frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred.

REGISTER 3-1: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 Unimplemented: Read as '0'

bit 4-0

TUN<4:0>: Frequency Tuning bits
01111 = Maximum frequency
01110 =
•
•
•
00001 =
00000 = Oscillator module is running at the manufacturer calibrated frequency.
11111 =
•
•
•
10000 = Minimum frequency

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets ⁽¹⁾
CONFIG ⁽²⁾	IOSCFS	CP	MCLRE	PWRTE	WDTE	FOSC2	FOSC1	FOSC0	—	—
OSCTUNE	_		_	TUN4	TUN3	TUN2	TUN1	TUN0	0 0000	u uuuu

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by oscillators.

Note 1: Other (non Power-up) Resets include MCLR Reset and Watchdog Timer Reset during normal operation.

2: See Configuration Word register (Register 12-1) for operation of all register bits.

U-0	U-0	R/W-1	R/W-1	U-0	R/W-1	R/W-1	R/W-1			
	—	WPUA5	WPUA4	—	WPUA2	WPUA1	WPUA0			
bit 7							bit 0			
Legend:										
R = Readable	bit	W = Writable	bit	U = Unimplemented bit, read as '0'						
-n = Value at P	-n = Value at POR '1' = Bit is set			0' = Bit is cleared $x = Bit is unknown$						
bit 7-6	Unimplemen	ted: Read as 'o)'							
bit 5-4	WPUA<5:4>:	Weak Pull-up	Control bits							
	1 = Pull-up er 0 = Pull-up dis	nabled sabled								

REGISTER 4-4: WPUA: WEAK PULL-UP PORTA REGISTER

bit 3Unimplemented: Read as '0'bit 2-0WPUA<2:0>: Weak Pull-up Control bits

- - 1 =Pull-up enabled 0 =Pull-up disabled

Note 1: Global RAPU must be enabled for individual pull-ups to be enabled.

- 2: The weak pull-up device is automatically disabled if the pin is in Output mode (TRISA = 0).
- **3:** The RA3 pull-up is enabled when configured as MCLR and disabled as an input in the Configuration Word.
- 4: WPUA<5:4> always reads '1' in XT, HS and LP Oscillator modes.

REGISTER 4-5: IOCA: INTERRUPT-ON-CHANGE PORTA REGISTER

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 Unimplemented: Read as '0'

bit 5-0 IOCA<5:0>: Interrupt-on-change PORTA Control bit

1 = Interrupt-on-change enabled

0 = Interrupt-on-change disabled

Note 1: Global Interrupt Enable (GIE) must be enabled for individual interrupts to be recognized.

2: IOCA<5:4> always reads '1' in XT, HS and LP Oscillator modes.

4.2.4.5 RA4/AN3⁽¹⁾/T1G/OSC2/CLKOUT

Figure 4-4 shows the diagram for this pin. The RA4 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the ADC⁽¹⁾

- a Timer1 gate (count enable)
- a crystal/resonator connection
- · a clock output
 - Note 1: PIC16F616/16HV616 only.



FIGURE 4-4: BLOCK DIAGRAM OF RA4

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1					
RAPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0					
bit 7							bit 0					
Legend:												
R = Readable	bit	W = Writable	e bit	U = Unimpler	mented bit, rea	d as '0'						
-n = Value at F	POR	'1' = Bit is se	t	'0' = Bit is cle	ared	x = Bit is unk	nown					
bit 7	RAPU: PORT	APU: PORTA Pull-up Enable bit										
	1 = PORTA p	1 = PORTA pull-ups are disabled										
	0 = PORTA p	0 = PORTA pull-ups are enabled by individual PORT latch values										
bit 6	INTEDG: Inte	errupt Edge Se	elect bit									
	1 = Interrupt	= Interrupt on rising edge of INT pin										
	0 = Interrupt	on falling edge	e of INT pin									
bit 5	TOCS: TMR0	TMR0 Clock Source Select bit										
	1 = Transition on T0CKI pin											
	0 = Internal ir	nstruction cycle	e clock (Fosc/	(4)								
bit 4	TOSE: TMR0	IR0 Source Edge Select bit										
	1 = Increment on high-to-low transition on T0CKI pin											
	0 = Increment on low-to-high transition on T0CKI pin											
bit 3	PSA: Presca	ler Assignmen	t bit									
	1 = Prescaler is assigned to the WDT											
	0 = Prescaler is assigned to the Timer0 module											
bit 2-0	PS<2:0>: Pr€	escaler Rate S	elect bits									
	BIT	VALUE TMR0 F	RATE WDT RA	TE								
	C	000 1:2	: 1:1									
	C	001 1:4	1:2									
	C	010 1:8	1:4									
	0											
	1	01 1:3	4 1.32									
	1	10 1:1	28 1:64									
	1	11 1 : 2	1 : 128	3								

REGISTER 5-1: OPTION_REG: OPTION REGISTER

TABLE 5-1: SUMMART OF REGISTERS ASSOCIATED WITH TIMER	TABLE 5-1:	SUMMARY OF REGISTERS	5 ASSOCIATED WITH TIMER
---	------------	----------------------	--------------------------------

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Valu POR,	e on BOR	Valu all o Res	e on ther sets
TMR0	Timer0 N	/lodules R	egister						xxxx	xxxx	uuuu	uuuu
INTCON	GIE	PEIE	TOIE	INTE	RAIE	T0IF	INTF	RAIF	0000	0000	0000	0000
OPTION_REG	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111	1111	1111	1111
TRISA	_	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11	1111	11	1111

Legend: -= Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Timer0 module.

R/W-0	R-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0				
C10N	C1OUT	C10E	C1POL	_	C1R	C1CH1	C1CH0				
bit 7							bit 0				
l egend:											
R = Reada	able bit	W = Writable	bit	U = Unimple	emented bit. rea	ad as '0'					
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit				x = Bit is unk	nown						
bit 7	C1ON: Comp	parator C1 Ena	ble bit								
	1 = Compara 0 = Compara	ator C1 is enabl ator C1 is disab	ed led								
bit 6	C1OUT: Com	nparator C1 Ou	tput bit								
	$\frac{ \mathbf{f} (C + \mathbf{POL}) ^2}{ \mathbf{C} ^2} = \frac{1}{2}$ $C1OUT = 0$ $\frac{ \mathbf{f} (C + \mathbf{POL}) ^2}{ \mathbf{C} ^2} = \frac{1}{2}$ $C1OUT = 1$ $C1OUT = 0$	<u>_ (Inverted pola</u> when C1VIN+ > when C1VIN+ < (non-inverted when C1VIN+ > when C1VIN+ <	r <u>nty):</u> C1VIN- C1VIN- polarity): C1VIN- C1VIN-								
bit 5	C1OE: Comp	10E: Comparator C1 Output Enable bit									
	1 = C1OUT is 0 = C1OUT is	s present on th s internal only	e C1OUT pin ^{(*}	1)							
bit 4	C1POL: Con	C1POL: Comparator C1 Output Polarity Select bit									
	1 = C1OUT 0 = C1OUT	ogic is inverted	rted								
bit 3	Unimplemer	nted: Read as '	0'								
bit 2	C1R: Compa	arator C1 Refer	ence Select bit	t (non-inverting	g input)						
	1 = C1VIN+ c 0 = C1VIN+ c	connects to C1 connects to C1	/REF output N+ pin								
bit 1-0	C1CH<1:0>:	Comparator C	1 Channel Sel	ect bit							
	00 = C12IN0 01 = C12IN1 10 = C12IN2 11 = C12IN3	- pin of C1 con - pin of C1 con - pin of C1 con - pin of C1 con	nects to C1VIN nects to C1VIN nects to C1VIN nects to C1VIN	√- √- √-							
Note 1:	Comparator outpu	ut requires the f	ollowing three	conditions: C	10E = 1, C10I	N = 1 and corres	sponding port				

REGISTER 8-1: CM1CON0: COMPARATOR 1 CONTROL REGISTER 0

Note 1: Comparator output requires the following three conditions: C1OE = 1, C1ON = 1 and corresponding port TRIS bit = 0.

9.2 ADC Operation

9.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/ DONE bit of the ADCON0 register to a '1' will start the analog-to-digital conversion.

Note:	The GO/DONE bit should not be set in the							
	same instruction that turns on the ADC.							
	Refer to Section 9.2.6 "A/D Conversion							
	Procedure".							

9.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/DONE bit
- Set the ADIF flag bit
- Update the ADRESH:ADRESL registers with new conversion result

9.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/DONE bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete analog-to-digital conversion sample. Instead, the ADRESH:ADRESL register pair will retain the value of the previous conversion. Additionally, a 2 TAD delay is required before another acquisition can be initiated. Following this delay, an input acquisition is automatically started on the selected channel.

Note:	A device Reset forces all registers to their							
	Reset state. Thus, the ADC module is							
	turned off and any pending conversion is							
	terminated.							

9.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

9.2.5 SPECIAL EVENT TRIGGER

The ECCP Special Event Trigger allows periodic ADC measurements without software intervention. When this trigger occurs, the GO/DONE bit is set by hardware and the Timer1 counter resets to zero.

Using the Special Event Trigger does not ensure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

See Section 10.0 "Enhanced Capture/Compare/ PWM (With Auto-Shutdown and Dead Band) Module (PIC16F616/16HV616 Only)" for more information.

9.2.6 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an analog-to-digital conversion:

- 1. Configure Port:
 - Disable pin output driver (See TRIS register)
 - Configure pin as analog
- 2. Configure the ADC module:
 - Select ADC conversion clock
 - Configure voltage reference
 - Select ADC input channel
 - Select result format
 - Turn on ADC module
- 3. Configure ADC interrupt (optional):
 - Clear ADC interrupt flag
 - Enable ADC interrupt
 - · Enable peripheral interrupt
 - Enable global interrupt⁽¹⁾
- 4. Wait the required acquisition time⁽²⁾.
- 5. Start conversion by setting the GO/DONE bit.
- 6. Wait for ADC conversion to complete by one of the following:
 - Polling the GO/DONE bit
 - Waiting for the ADC interrupt (interrupts enabled)
- 7. Read ADC Result
- 8. Clear the ADC interrupt flag (required if interrupt is enabled).
 - **Note 1:** The global interrupt may be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.
 - 2: See Section 9.3 "A/D Acquisition Requirements".

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PRSEN	PDC6	PDC5	PDC4	PDC3	PDC2	PDC1	PDC0
bit 7							bit 0
Logond							

REGISTER 10-3: PWM1CON: ENHANCED PWM CONTROL REGISTER

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	1 as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 PRSEN: PWM Restart Enable bit

1 = Upon auto-shutdown, the ECCPASE bit clears automatically once the shutdown event goes away; the PWM restarts automatically

0 = Upon auto-shutdown, ECCPASE must be cleared in software to restart the PWM

bit 6-0 PDC<6:0>: PWM Delay Count bits

PDCn = Number of Fosc/4 (4 * Tosc) cycles between the scheduled time when a PWM signal **should** transition active and the **actual** time it transitions active

TABLE 10-7: SUMMARY OF REGISTERS ASSOCIATED WITH PWM

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
CCP1CON ⁽¹⁾	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0000 0000	0000 0000
CCPR1L ⁽¹⁾	Capture/Cor	mpare/PWM F	Register 1 Lo	w Byte					xxxx xxxx	uuuu uuuu
CCPR1H ⁽¹⁾	Capture/Cor	mpare/PWM F	Register 1 Hiç	gh Byte					xxxx xxxx	uuuu uuuu
CM1CON0	C10N	C1OUT	C10E	C1POL	-	C1R	C1CH1	C1CH0	0000 -000	0000 -000
CM2CON0	C2ON	C2OUT	C2OE	C2POL	-	C2R	C2CH1	C2CH0	0000 -000	0000 -000
CM2CON1	MC1OUT	MC2OUT		T1ACS	C1HYS	C2HYS	T1GSS	C2SYNC	00-0 0010	00-0 0010
ECCPAS ⁽¹⁾	ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1	PSSBD0	0000 0000	0000 0000
INTCON	GIE	PEIE	TOIE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 0000
PIE1	_	ADIE ⁽¹⁾	CCP1IE ⁽¹⁾	C2IE	C1IE	_	TMR2IE ⁽¹⁾	TMR1IE	-000 0-00	0000 0-00
PIR1	_	ADIF ⁽¹⁾	CCP1IF ⁽¹⁾	C2IF	C1IF	_	TMR2IF ⁽¹⁾	TMR1IF	-000 0-00	0000 0-00
PWM1CON ⁽¹⁾	PRSEN	PDC6	PDC5	PDC4	PDC3	PDC2	PDC1	PDC0	0000 0000	0000 0000
T2CON ⁽¹⁾		TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
TMR2 ⁽¹⁾	Timer2 Module Register								0000 0000	0000 0000
TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111
TRISC	_	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	11 1111

Legend: -= Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Capture, Compare and PWM. Note 1: PIC16F616/16HV616 only.

12.3.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, simply connect the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See **Section 15.0** "**Electrical Specifications**" for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until VDD reaches VBOR (see **Section 12.3.4** "**Brown-out Reset (BOR)**").

Note: The POR circuit does not produce an internal Reset when VDD declines. To reenable the POR, VDD must reach Vss for a minimum of 100 μs.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure proper operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607, *"Power-up Trouble Shooting"* (DS00607).

12.3.2 MCLR

PIC16F610/616/16HV610/616 has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{\text{MCLR}}$ pin low.

Voltages applied to the MCLR pin that exceed its specification can result in both MCLR Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 12-2, is suggested.

An internal $\overline{\text{MCLR}}$ option is enabled by clearing the $\overline{\text{MCLRE}}$ bit in the Configuration Word register. When $\overline{\text{MCLRE}} = 0$, the Reset signal to the chip is generated internally. When the $\overline{\text{MCLRE}} = 1$, the RA3/ $\overline{\text{MCLR}}$ pin becomes an external Reset input. In this mode, the RA3/ $\overline{\text{MCLR}}$ pin has a weak pull-up to VDD.

FIGURE 12-2:



12.3.3 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from an internal RC oscillator. For more information, see **Section 3.4** "Internal Clock Modes". The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit, PWRTE, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip due to:

- VDD variation
- Temperature variation
- · Process variation

See DC parameters for details (Section 15.0 "Electrical Specifications").

Note:	Voltage spikes below Vss at the MCLR
	pin, inducing currents greater than 80 mA,
	may cause latch-up. Thus, a series resis-
	tor of 50-100 Ω should be used when
	applying a "low" level to the MCLR pin,
	rather than pulling this pin directly to Vss.

12.4 Interrupts

The PIC16F610/616/16HV610/616 has multiple sources of interrupt:

- External Interrupt RA2/INT
- Timer0 Overflow Interrupt
- PORTA Change Interrupts
- 2 Comparator Interrupts
- A/D Interrupt (PIC16F616/16HV616 only)
- Timer1 Overflow Interrupt
- Timer2 Match Interrupt (PIC16F616/16HV616 only)
- Enhanced CCP Interrupt (PIC16F616/16HV616 only)

The Interrupt Control register (INTCON) and Peripheral Interrupt Request Register 1 (PIR1) record individual interrupt requests in flag bits. The INTCON register also has individual and global interrupt enable bits.

The Global Interrupt Enable bit, GIE of the INTCON register, enables (if set) all unmasked interrupts, or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in the INTCON register and PIE1 register. GIE is cleared on Reset.

When an interrupt is serviced, the following actions occur automatically:

- The GIE is cleared to disable any further interrupt.
- The return address is pushed onto the stack.
- The PC is loaded with 0004h.

The Return from Interrupt instruction, RETFIE, exits the interrupt routine, as well as sets the GIE bit, which re-enables unmasked interrupts.

The following interrupt flags are contained in the INT-CON register:

- INT Pin Interrupt
- PORTA Change Interrupt
- Timer0 Overflow Interrupt

The peripheral interrupt flags are contained in the special register, PIR1. The corresponding interrupt enable bit is contained in special register, PIE1.

The following interrupt flags are contained in the PIR1 register:

- A/D Interrupt
- 2 Comparator Interrupts
- Timer1 Overflow Interrupt
- Timer2 Match Interrupt
- Enhanced CCP Interrupt

For external interrupt events, such as the INT pin or PORTA change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends upon when the interrupt event occurs (see Figure 12-8). The latency is the same for one or twocycle instructions. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

- Note 1: Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.
 - 2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The interrupts, which were ignored, are still pending to be serviced when the GIE bit is set again.

For additional information on Timer1, Timer2, comparators, ADC, Enhanced CCP modules, refer to the respective peripheral section.

12.4.1 RA2/INT INTERRUPT

The external interrupt on the RA2/INT pin is edgetriggered; either on the rising edge if the INTEDG bit of the OPTION register is set, or the falling edge, if the INTEDG bit is clear. When a valid edge appears on the RA2/INT pin, the INTF bit of the INTCON register is set. This interrupt can be disabled by clearing the INTE control bit of the INTCON register. The INTF bit must be cleared by software in the Interrupt Service Routine before re-enabling this interrupt. The RA2/INT interrupt can wake-up the processor from Sleep, if the INTE bit was set prior to going into Sleep. See **Section 12.7** "**Power-Down Mode (Sleep)**" for details on Sleep and Figure 12-9 for timing of wake-up from Sleep through RA2/INT interrupt.

Note: The ANSEL register must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0' and cannot generate an interrupt.

12.4.2 TIMER0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set the T0IF bit of the INTCON register. The interrupt can be enabled/disabled by setting/clearing T0IE bit of the INTCON register. See **Section 5.0 "Timer0 Module"** for operation of the Timer0 module.

12.4.3 PORTA INTERRUPT-ON-CHANGE

An input change on PORTA sets the RAIF bit of the INTCON register. The interrupt can be enabled/ disabled by setting/clearing the RAIE bit of the INTCON register. Plus, individual pins can be configured through the IOCA register.

Note: If a change on the I/O pin should occur when any PORTA operation is being executed, then the RAIF interrupt flag may not get set.



14.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

14.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

14.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel[®] standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

14.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

14.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- · Support for fixed-point and floating-point data
- Command line interface
- · Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

FIGURE 15-3: PIC16F610/616 FREQUENCY TOLERANCE GRAPH,



FIGURE 15-4: PIC16HV610/616 FREQUENCY TOLERANCE GRAPH,





FIGURE 15-8: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING





Param	Device	Unite	Min Tur	Max	Condition			
No.	Characteristics	Units	IVIIN	тур	Max	Vdd	Note	
D010			—	13	58	2.0		
	Supply Current (IDD)	μA	_	19	67	3.0	IDD LP OSC (32 kHz)	
			_	32	92	5.0		
D011			—	135	316	2.0		
		μA	_	185	400	3.0	IDD XT OSC (1 MHz)	
			_	300	537	5.0		
D012			_	240	495	2.0		
		μΑ		360	680	3.0	IDD XT OSC (4 MHz)	
		mA		0.660	1.20	5.0		
D013			_	75	158	2.0		
		μA	_	155	338	3.0	IDD EC OSC (1 MHz)	
			_	345	792	5.0		
D014		μA -	—	185	357	2.0		
			_	325	625	3.0	IDD EC OSC (4 MHz)	
		mA	—	0.665	1.30	5.0		
D016			—	245	476	2.0		
		μA		360	672	3.0	IDD INTOSC (4 MHz)	
				620	1.10	5.0		
D017		μΑ	_	395	757	2.0		
		mΔ		0.620	1.20	3.0	IDD INTOSC (8 MHz)	
				1.20	2.20	5.0		
D018			—	175	332	2.0		
		μΑ	—	285	518	3.0	IDD EXTRC (4 MHz)	
			—	530	972	5.0		
D019		mA	_	2.20	4.10	4.5		
		IIIA		2.80	4.80	5.0		

TABLE 15-14: DC CHARACTERISTICS FOR IDD SPECIFICATIONS FOR PIC16F616 – H (High Temp.)







14-Lead Plastic Small Outline (SL) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension	n Limits	MIN	NOM	MAX
Number of Pins	Ν		14	
Pitch	е		1.27 BSC	
Overall Height	Α	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Foot Angle	φ	0°	-	8°
Lead Thickness	С	0.17	-	0.25
Lead Width	b	0.31	_	0.51
Mold Draft Angle Top	α	5°	_	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic.

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.

- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>×</u>	<u>/xx</u>	<u>xxx</u>		Exa	mples:
Device	Temperature Pa Range	ackage	Pattern		a) b)	PIC16F610-E/P 301 = Extended Temp., PDIP package, 20 MHz, QTP pattern #301 PIC16F616-E/P 301 = Extended Temp., PDIP package, 20 MHz, QTP pattern #301
Device:	PIC16F610/616/16H 616T ⁽¹⁾	IV610/616	, PIC16F610/616/16H	V610/	c) d)	PIC16HV610-E/P 301 = Extended Temp., PDIP package, 20 MHz, QTP pattern #301 PIC16HV616-E/P 301 = Extended Temp., PDIP package, 20 MHz, QTP pattern #301 PIC16F610 //SI = Inductrial Temp. SOIC
Temperature Range:	$ \begin{array}{rcl} I & = -40^{\circ}C \text{ to} \\ E & = -40^{\circ}C \text{ to} \\ H & = -40^{\circ}C \text{ to} \end{array} $	+85°C +125°C +150°C	(Industrial) (Extended) (High Temp.) ⁽²⁾		e) f) g)	PIC16F610-I/SL = Industrial Temp., SOIC package, 20 MHz PIC16F616-I/SL = Industrial Temp., SOIC package, 20 MHz PIC16HV610-I/SL = Industrial Temp., SOIC
Package:	ML = Quad Fla P = Plastic D SL = 14-lead S ST = Thin Shri	at No Lead IP (PDIP) Small Outli ink Small (ls (QFN) ine (3.90 mm) (SOIC) Dutline (4.4 mm) (TSS	OP)	h) i) j)	PIC16HV616-I/SL = Industrial Temp., SOIC package, 20 MHz PIC16F610T-E/ST Tape and Reel, Extended Temp., TSSOP package, 20 MHz PIC16F616T-E/ST Tape and Reel, Extended
Pattern:	QTP, SQTP or ROM (blank otherwise)	Code; Sp	ecial Requirements		k) I) m)	PiC16HV610T-E/ST Tape and Reel, Extended Temp., TSSOP package, 20 MHz PiC16HV616T-E/ST Tape and Reel, Extended Temp., TSSOP package, 20 MHz PiC16F616 - H/SL = High Temp., SOIC pack- age, 20 MHz.
					Note	 T = in tape and reel for TSSOP, SOIC and QFN packages only. High Temp. available for PIC16F616 only.